



OL-PMCM650VNE

WLCSP6: wafer level chip-size package; 6 bumps (3 x 2)

7 June 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP6
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	25-3-2015
Manufacturer package code	WLCSP6

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.45	-	1.48	1.51	mm
E	package width	0.95	-	0.98	1.01	mm
A	seated height	0.315	-	0.345	0.375	mm
A ₂	package height	0.13	-	0.145	0.16	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	6	-	

2. Package outline

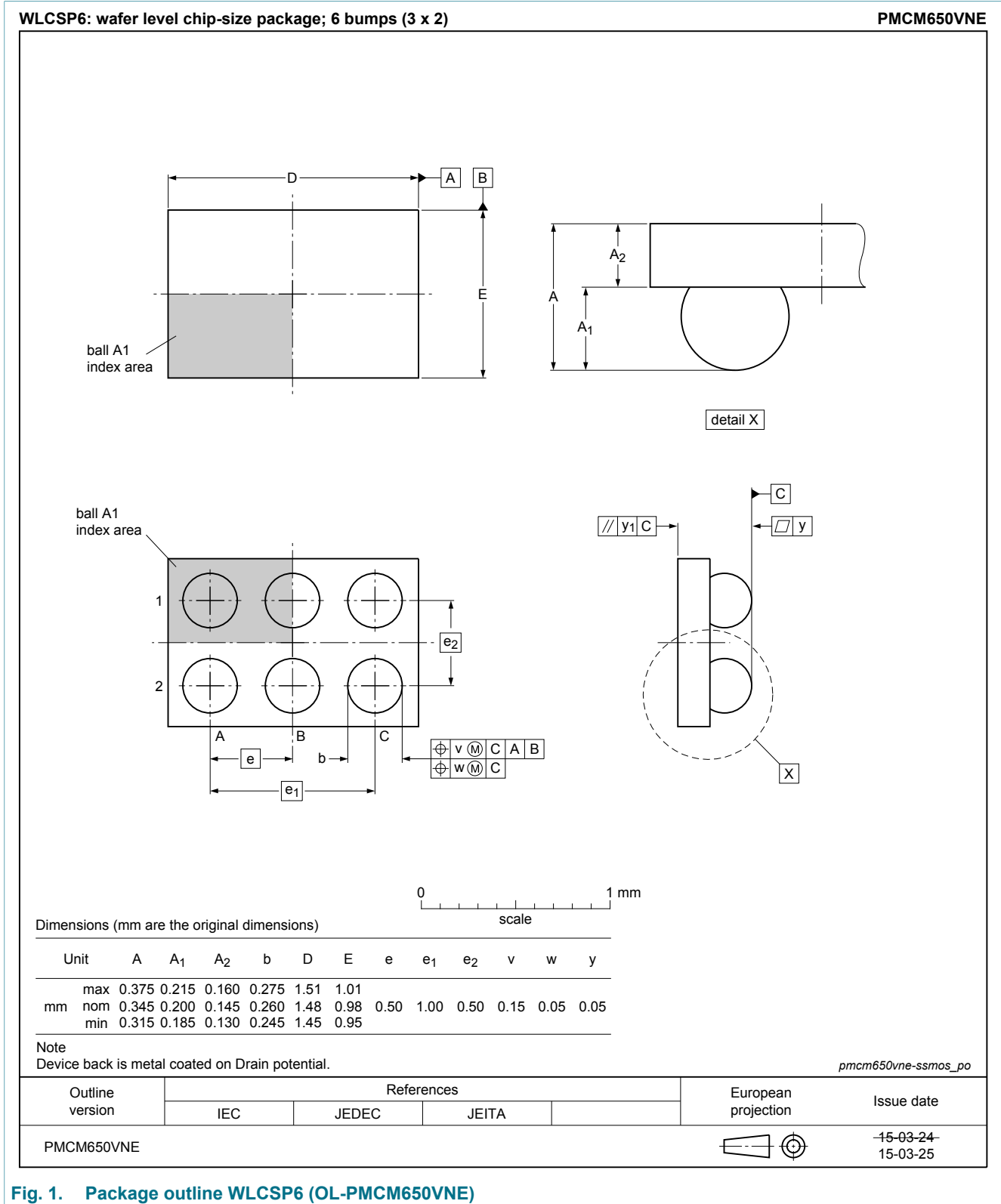
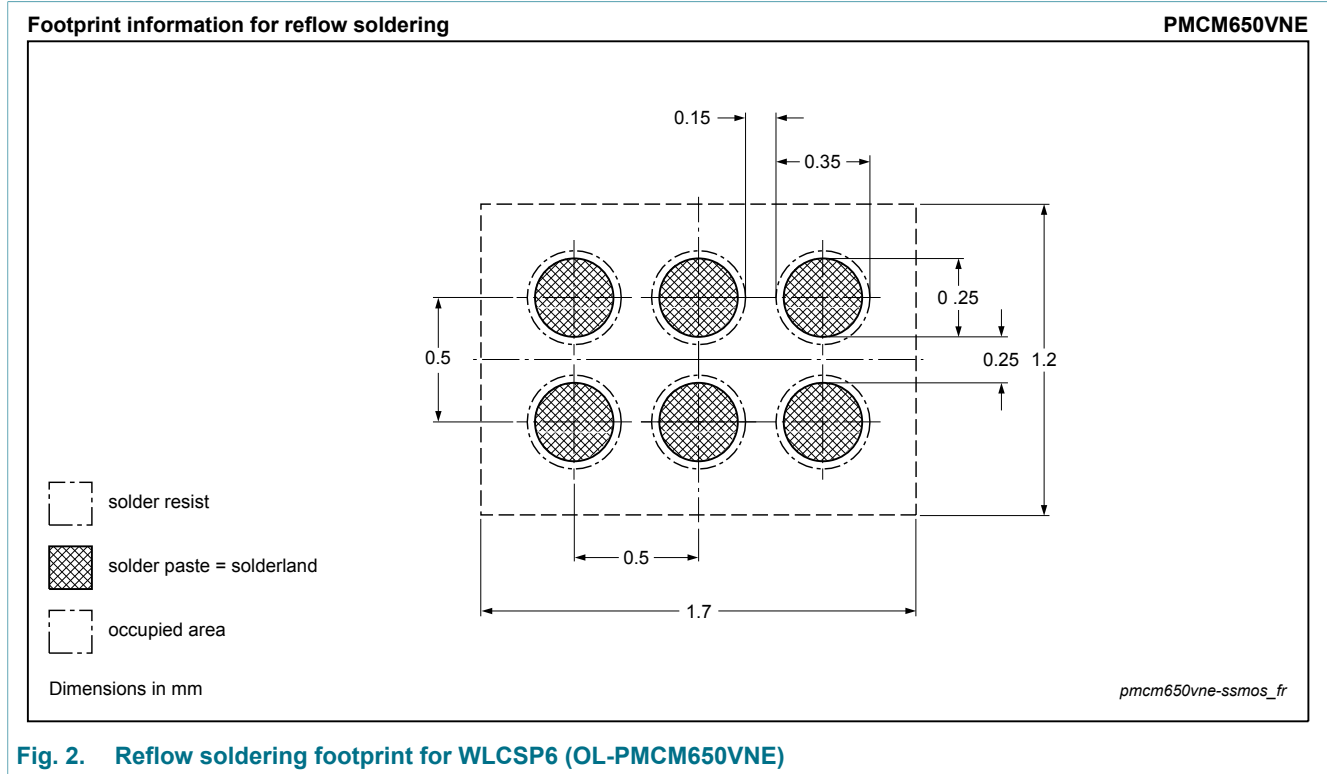


Fig. 1. Package outline WLCSP6 (OL-PMCM650VNE)

3. Soldering



4. Legal information

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